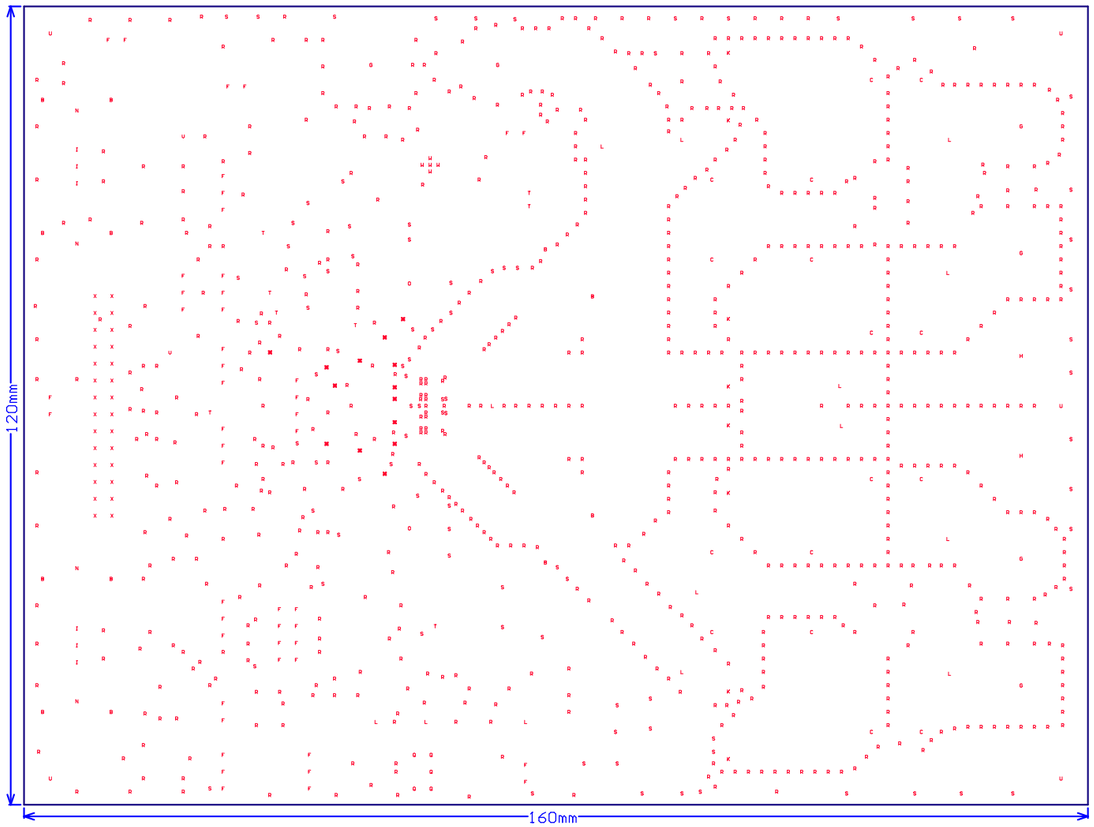
M12 Stackup

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	2.74mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	2.74mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



Drill Guide

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
W	5	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
S	90	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
R	729	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
T	8	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
✖	14	17.72mil (0.450mm)	PTH	Round	Top Layer - Bottom Layer	
U	2	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
Q	5	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
F	48	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
X	28	40.94mil (1.040mm)	PTH	Round	Top Layer - Bottom Layer	
C	16	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
I	6	42.13mil (1.070mm)	PTH	Round	Top Layer - Bottom Layer	
K	8	53.15mil (1.350mm)	PTH	Round	Top Layer - Bottom Layer	
L	14	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
N	4	66.93mil (1.700mm)	PTH	Round	Top Layer - Bottom Layer	
B	12	78.74mil (2.000mm)	PTH	Round	Top Layer - Bottom Layer	
O	2	118.11mil (3.000mm)	PTH	Round	Top Layer - Bottom Layer	
U	5	127.95mil (3.250mm)	PTH	Round	Top Layer - Bottom Layer	
H	2	144.00mil (3.658mm)	PTH	Round	Top Layer - Bottom Layer	
G	6	195.00mil (4.953mm)	PTH	Round	Top Layer - Bottom Layer	
	1004 Total					

M10 Fab Notes

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 15 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[ ] GREEN [X] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: TPA3255D2DDV Evaluation Module
DESIGNED FOR: Public Release
FILE NAME: AAP053A_EVM.PcbDoc

ENGINEER: DAMIAN LEWIS	LAYOUT BY: LDN
SCALE: 1.12	ALTIUM DESIGNER VERSION: 16.0.9.368

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AAP053	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	M1 Board Outline M2 Board Dimensions		
PLOT NAME = Fabrication Drawing	GENERATED : 6/14/2016 9:49:11 AM	TEXAS INSTRUMENTS	

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